

AA3528P3S

3.5 x 2.8 mm Phototransistor



DESCRIPTION

- Made with NPN silicon phototransistor chips

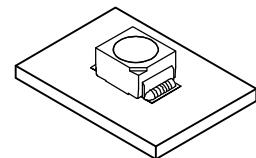
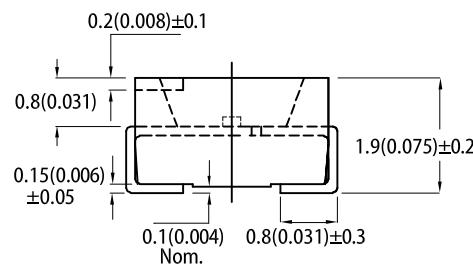
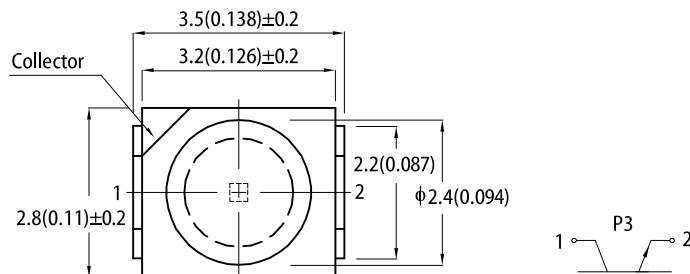
FEATURES

- Mechanically and spectrally matched to the infrared emitting LED lamp
- Package: 2000 pcs / reel
- Package matched with IR emitter AA3528F3S
- Moisture sensitivity level: 3
- Water clear lens
- Halogen-free
- RoHS compliant

APPLICATIONS

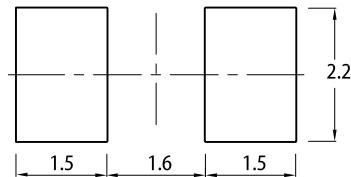
- Infrared applied systems
- Optoelectronic switches
- Photodetector control circuits
- Sensor technology

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)



Notes:

- All dimensions are in millimeters (inches).
- Tolerance is ±0.25(0.01") unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
- The device has a single mounting surface. The device must be mounted according to the specifications.

ABSOLUTE MAXIMUM RATINGS at $T_A=25^\circ\text{C}$

Parameter	Max.Ratings	Units
Collector-to-Emitter Voltage	30	V
Emitter-to-Collector Voltage	5	V
Power Dissipation at(or below) 25°C Free Air Temperature	100	mW
Operating Temperature	-40 to +85	°C
Storage Temperature	-40 to +85	°C

Note:

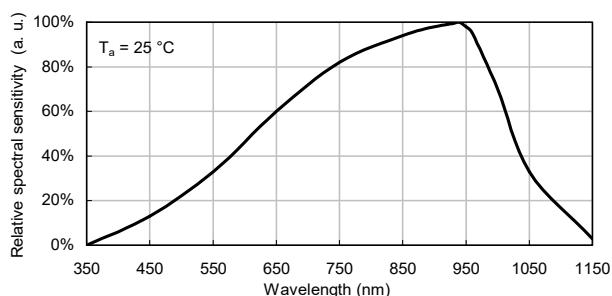
- Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

ELECTRICAL / OPTICAL CHARACTERISTICS at $T_A=25^\circ\text{C}$

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Collector-to-Emitter Breakdown Voltage	$V_{BR\ CEO}$	30	-	-	V	$I_C = 100\mu\text{A}$ $E_e = 0\text{mW/cm}^2$
Emitter-to-Collector Breakdown Voltage	$V_{BR\ ECO}$	5	-	-	V	$I_E = 100\mu\text{A}$ $E_e = 0\text{mW/cm}^2$
Collector-to-Emitter Saturation Voltage	$V_{CE\ (SAT)}$	-	-	0.8	V	$I_C = 2\text{mA}$ $E_e = 20\text{mW/cm}^2$
Collector Dark Current	I_{CEO}	-	-	100	nA	$V_{CE} = 10\text{V}$ $E_e = 0\text{mW/cm}^2$
Rise Time(10% to 90%)	T_R	-	15	-	μS	$V_{CE} = 5\text{V}$ $I_C = 1\text{mA}$ $R_L = 1000\Omega$
Fall Time(90% to 10%)	T_F	-	15	-	μS	
On State Collector Current	$I_{(ON)}$	0.2	0.4	-	mA	$V_{CE} = 5\text{V}$ $E_e = 1\text{mW/cm}^2$ $\lambda = 940\text{nm}$
Range of Spectral Bandwidth	$\lambda_{0.1}$	420	-	1120	nm	-
Wavelength of Peak Sensitivity	λ_p	-	940	-	nm	-

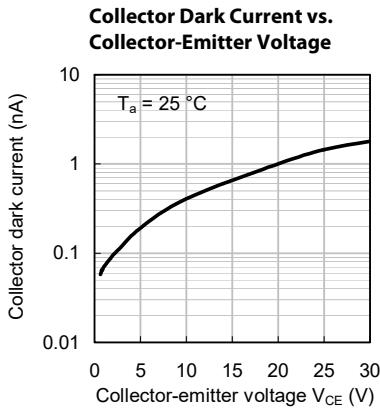
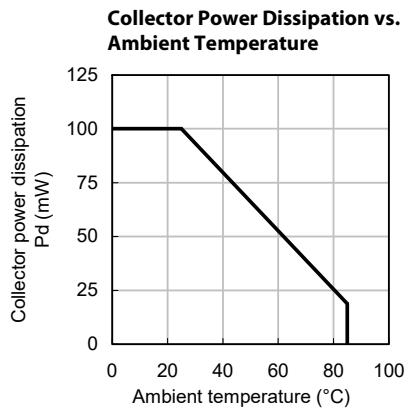
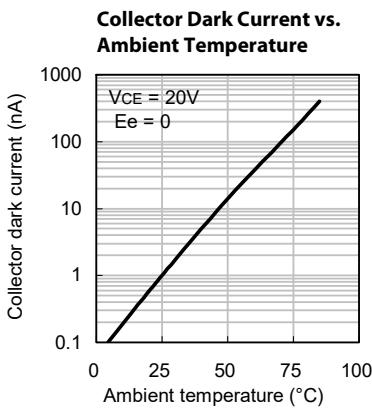
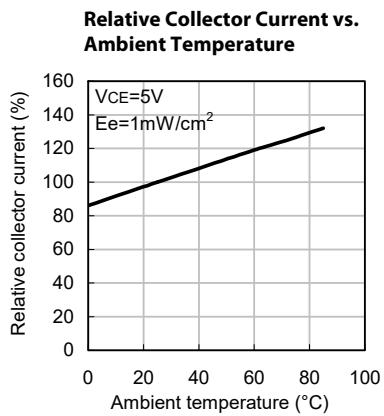
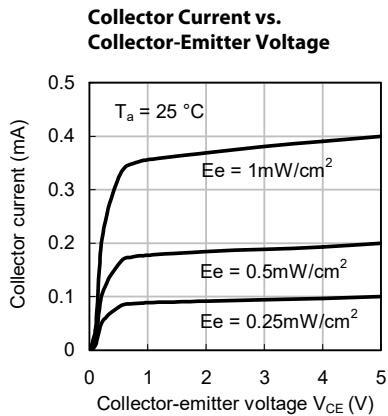
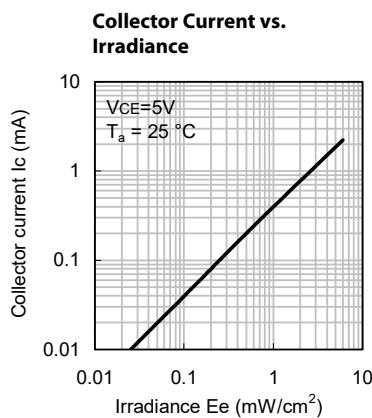
TECHNICAL DATA

RELATIVE SPECTRAL SENSITIVITY vs. WAVELENGTH

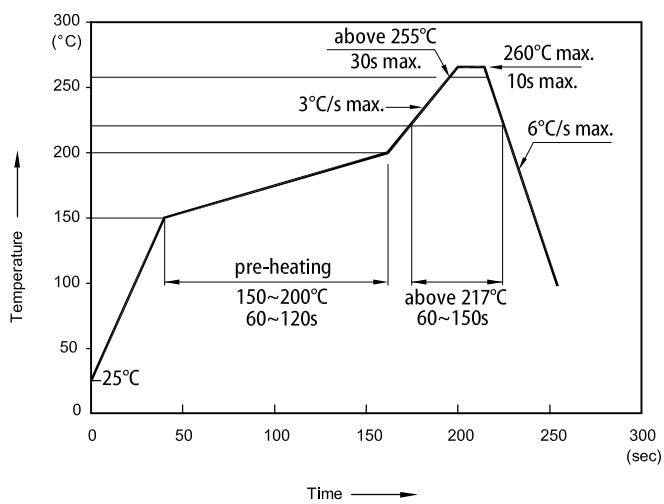


TECHNICAL DATA

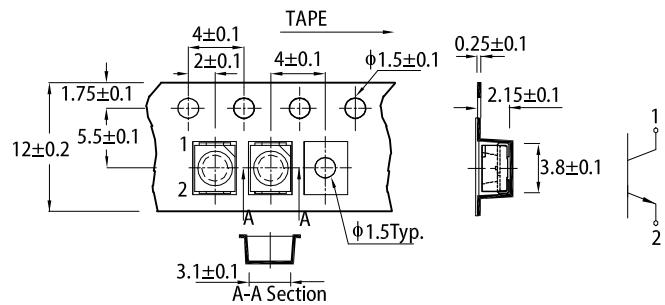
PHOTOTRANSISTOR



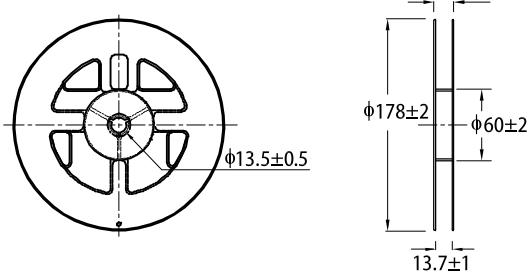
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



TAPE SPECIFICATIONS (units : mm)



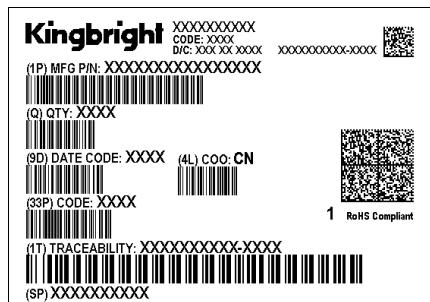
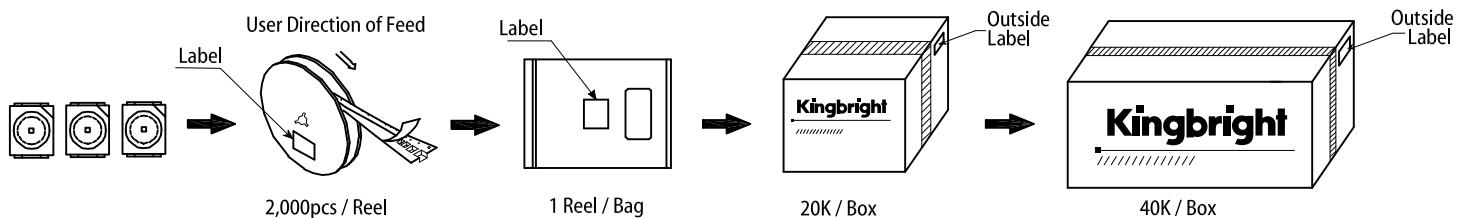
REEL DIMENSION (units : mm)



Notes:

1. Don't cause stress to the LEDs while it is exposed to high temperature.
2. The maximum number of reflow soldering passes is 2 times.
3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

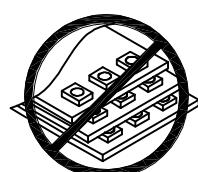
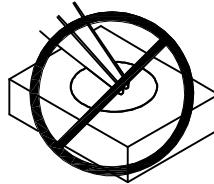
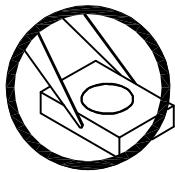
PACKING & LABEL SPECIFICATIONS



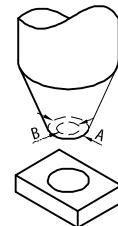
HANDLING PRECAUTIONS

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4-1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4-2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4-3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.
5. As silicone encapsulation is permeable to gases, some corrosive substances such as H₂S might corrode silver plating of lead frame. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.



PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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